



CLAIM AMENDMENTS

Claims 1 -7 (cancelled)

Claim 8 (currently amended) Dip soldering apparatus comprising:

a reservoir for molten solder and
an elongate plate provided in the reservoir and positioned at a surface of the molten solder into which, and surface component leads selectively movable between a raised and lowered condition for being are to be dipped into said solder, the plate having an upwardly facing edge and side surfaces extending downwards from the plate edge, the plate being positioned and dimensioned so that adjacent component leads to be soldered pass to each side of the plate edge and the plate surface being of a material which is wetted by the molten solder.

Claim 9 (currently amended) Dip soldering apparatus comprising a nozzle having an outlet through which solder is flowed in use, and leads to be soldered selectively removable between a raised and lowered condition for being dipped into the solder surface at the nozzle outlet, wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads of a component to be soldered.

Claim 10 (previously presented) Apparatus as claimed in claim 9, wherein the member is below the level of the solder surface as the solder flows through the nozzle outlet.

Claim 11 (previously presented) Apparatus as claimed in claim 9, wherein the member is movable relative to the solder surface.

Claim 12 (previously presented) Apparatus as claimed in claim in claim 9, wherein the member is positioned so as to project through the solder surface as the

leads are withdrawn from the solder.

Claim 13 (previously presented) Apparatus as claimed in claim 12, wherein means is provided to lower the solder surface to effect withdrawal of the leads from the solder.

Claim 14 (previously presented) Apparatus as claimed in claim 9, wherein the member is an elongated plate having an upwardly facing edge.

Claim 15 (previously presented) Apparatus as claimed in claim 9, wherein the member has a honeycomb structure.

Claim 16 (new) The apparatus of claim 8, wherein said plate is movable relative to the solder surface.

Claim 17 (new) The apparatus of claim 8, wherein said plate is positioned so as to project through the solder surface as the component leads are withdrawn from the solder.

Claim 18 (new) The apparatus of claim 8, further including means for lowering the solder surface in order to effect withdrawal of the component leads from the solder.

Claim 19 (new) The apparatus of claim 8, wherein the member has a honeycomb structure.

Claim 20 (new) Dip soldering apparatus comprising:
a nozzle having an outlet through which solder is flowed in use, leads to be soldered being dipped into the solder surface at the nozzle outlet, wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads of a component to be soldered;

wherein said member is movable relative to said solder surface.

Claim 21 (new) The apparatus of claim 20, wherein said member is disposed below the level of the solder surface as the solder flows through the nozzle outlet.

Claim 22 (new) The apparatus of claim 20, wherein said member is positioned in order to project through the solder surface as said component leads are withdrawn from the solder.

Claim 23 (new) The apparatus of claim 20, further including means for lowering the solder surface in order to effect withdrawal of the leads from the solder.

Claim 24 (new) The apparatus of claim 20, wherein said member has a honeycomb structure.

Claim 25 (new) Dip soldering apparatus comprising a nozzle having an outlet through which solder is flowed in use, leads to be soldered being dipped into the solder surface at the nozzle outlet, wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads of a component to be soldered;

said apparatus further including means for lowering the solder surface in order to effect withdrawal of the leads from the solder.

Claim 26 (new) The apparatus of claim 25, wherein said member is disposed below the level of the solder surface as the solder flows through the nozzle outlet.

Claim 27 (new) The apparatus of claim 25, wherein said member is movable relative to the solder surface.

Claim 28 (new) The apparatus of claim 25, wherein said member is positioned for projecting through the solder surface as the leads are withdrawn from the solder.

Claim 29 (new) Dip soldering apparatus comprising:

a reservoir for molten solder and

an elongate plate provided in the reservoir and positioned at a surface of the molten solder, and surface component leads for being dipped into said solder, the plate having an upwardly facing edge and side surfaces extending downwards from the plate edge, the plate being positioned and dimensioned so that adjacent component leads to be soldered pass to each side of the plate edge and the plate surface being of a material which is wetted by the molten solder;

wherein said plate is movable relative to the solder surface.

Claim 30 (new) The apparatus of claim 29, wherein said plate is positioned for projecting through the solder surface as the leads are withdrawn from the solder.

Claim 31 (new) The apparatus of claim 29, further including means for lowering the solder surface for effecting withdrawal of the component leads from the solder.

Claim 32 (new) Dip soldering apparatus comprising:

a reservoir for molten solder; and

an elongate plate provided in the reservoir and positioned at a surface of the molten solder, surface component leads for being dipped into said solder, the plate having an upwardly facing edge and side surfaces extending downwards from the plate edge, the plate being positioned and dimensioned so that adjacent component leads to be soldered pass to each side of the plate edge and the plate surface being of a material which is wetted by the molten solder;

said apparatus further including means for lowering the solder surface for effecting withdrawal of the leads from the solder.

Claim 33 (new) The apparatus of claim 32, wherein said plate is movable relative to the solder surface.

Claim 34 (new) The apparatus of claim 32, wherein said plate is positioned for

projecting through the solder surface as said component leads are withdrawn from said solder.

Claim 35 (new) Dip soldering apparatus comprising a nozzle having an outlet through which solder is flowed in use, leads to be soldered being dipped into the solder surface at the nozzle outlet, wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads of a component to be soldered; wherein said member has a honeycomb structure.